

# PATENT ASSIGNMENT

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Rae-Hyuk Lee	11/28/2008
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Dongbu HiTek Co., Ltd.
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<b>City:</b>	Seoul
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	135-280
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12344565
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	604-0307
<b>NAME OF SUBMITTER:</b>	Daniel H. Sherr
<b>Total Attachments: 3</b> source=20090416154905#page1.tif source=20090416154905#page2.tif source=20090416154905#page3.tif	

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**PATENT**  
**REEL: 022556 FRAME: 0215**

Docket No.: 604-0307  
Application No.: 12/344,565  
Filing Date: 12/28/2008

**ASSIGNMENT**

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Rae-Hyuk Lee residing at B-901, Diatt Gallery 3-cha, Jung-dong, Wonmi-gu, Bucheon-si, Gyeonggi-do, Republic of Korea

who has made certain new and useful inventions, hereby sell, assign and transfer unto

**Dongbu HiTek Co., Ltd.**

having an address at

891-10, Daechi-dong, Gangnam-gu, Seoul, Korea 135-280

its successors and assigns (hereinafter designated "ASSIGNEE" the entire right, title and interest for the United States of American as defined in 35 U.S.C. 100 in the invention entitled

**SEMICONDUCTOR CHIP PACKAGE AND METHOD FOR  
MANUFACTURING THEREOF**

for which an application for a United States Patent was filed on December 28, 2008,  
identified as U.S. Patent Serial Number 12/344,565,

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and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and/or that claim priority thereto and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof and/or that claim priority thereto, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, and associated foreign patent applications, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

AND the undersigned hereby grants the firm of SHERR & NOURSE, PLLC the power to insert on this assignment any further identification that may be necessary or desirable in order to comply with the rules of any issuing authority, including the United States Patent and Trademark Office, for recordation of this document.

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SIGNED on the dates indicated aside our signatures:

INVENTOR

DATE

1)



*Nov. 28, 2008*

Rae-Hyuk Lee